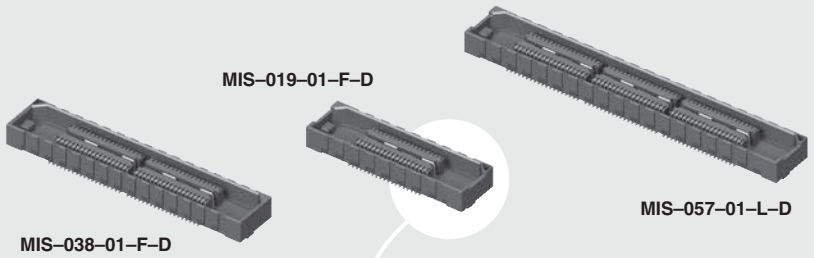
samtec

QSTRIP®



(0.635 mm) .025"

MIS SERIES

MIXED TECHNOLOGY SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
275 VAC
Max Cycles:
100
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (019-057)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE
(MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 µ" (0.76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

Board Mates:
MIT

Standoffs:
SO

RUGGEDIZED BY SAMTEC

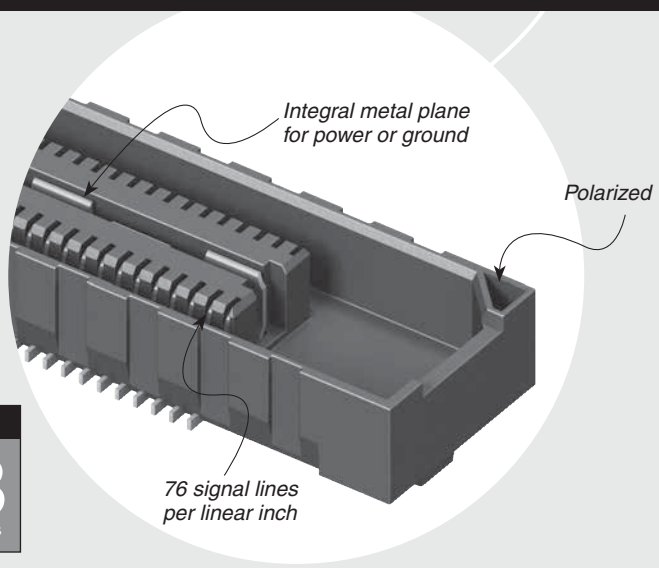
- Mixed technology footprint

HIGH-SPEED CHANNEL PERFORMANCE

MIT/MIS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

28 Gbps



MIS	–	NO. OF POSITIONS PER ROW	–	01	–	PLATING OPTION	–	D	–	OTHER OPTION

–019, –038, –057
(38 total positions per bank)

–F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

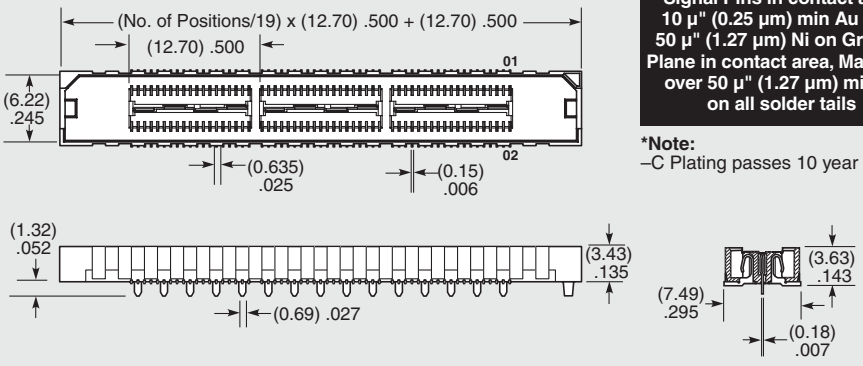
–L
= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, 10 µ" (0.25 µm) min Au over 50 µ" (1.27 µm) Ni on Ground Plane in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails

–K
= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad

–TR
= Tape & Reel

***Note:**
–C Plating passes 10 year MFG testing



MATED HEIGHT*		
MIS LEAD STYLE	MIT LEAD STYLE	
	–01	–02
–01	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

Note:
Some lengths, styles and options are non-standard, non-returnable.